

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>SHU-JENN YU</td> <td>02/05/2013</td> </tr> <tr> <td>MENG-WEI HSIEH</td> <td>02/05/2014</td> </tr> <tr> <td>SHIH-HSIEN YANG</td> <td>02/05/2014</td> </tr> <tr> <td>HUA-CHOU TSENG</td> <td>02/05/2014</td> </tr> <tr> <td>CHIH-PING CHAO</td> <td>02/05/2014</td> </tr> </tbody> </table>		Name	Execution Date	SHU-JENN YU	02/05/2013	MENG-WEI HSIEH	02/05/2014	SHIH-HSIEN YANG	02/05/2014	HUA-CHOU TSENG	02/05/2014	CHIH-PING CHAO	02/05/2014
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<table border="1"> <tr> <td>Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.</td> </tr> <tr> <td>Street Address:</td> <td>NO. 8, LI-HSIN RD. VI, HSINCHU SCIENCE PARK</td> </tr> <tr> <td>City:</td> <td>HSINCHU</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	Street Address:	NO. 8, LI-HSIN RD. VI, HSINCHU SCIENCE PARK	City:	HSINCHU	State/Country:	TAIWAN	Postal Code:	300		
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PROPERTY NUMBERS Total: 1													
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Application Number:	14177451												
CORRESPONDENCE DATA													
Fax Number:	(703)518-5499												
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NAME OF SUBMITTER:	RANDY A. NORANBROCK												

PATENT

Signature:	/Randy A. Noranbrock/
Date:	02/11/2014
Total Attachments: 1 source=EfiledAssgn#page1.tif	

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- | | |
|--------------------|-------------------|
| 1) Shu-Jenn YU | 4) Hua-Chou TSENG |
| 2) Meng-Wei HSIEH | 5) Chih-Ping CHAO |
| 3) Shih-Hsien YANG | |

who has made a certain new and useful invention, hereby sells, assigns and transfers unto TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD., having a place of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

ISOLATION STRUCTURE

(a) for which an application for United States Letters Patent was filed on February 11, 2014, and identified by United States Patent Application No. 14/177,451; or

(b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, and continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

- | | |
|--|--------------------------------|
| 1) ✓ <u>Shu Jenn Yu</u>
Name: Shu-Jenn YU | ✓ <u>2014. 02. 05</u>
Date: |
| 2) ✓ <u>Meng-Wei Hsieh</u>
Name: Meng-Wei HSIEH | ✓ <u>2014. 02. 05</u>
Date: |
| 3) ✓ <u>Shih-Hsien Yang</u>
Name: Shih-Hsien YANG | ✓ <u>2014. 02. 05</u>
Date: |
| 4) ✓ <u>Hua-Chou Tseeng</u>
Name: Hua-Chou TSENG | ✓ <u>2014. 02. 05</u>
Date: |
| 5) ✓ <u>Chih Ping Chao</u>
Name: Chih-Ping CHAO | ✓ <u>2014. 02. 05</u>
Date: |